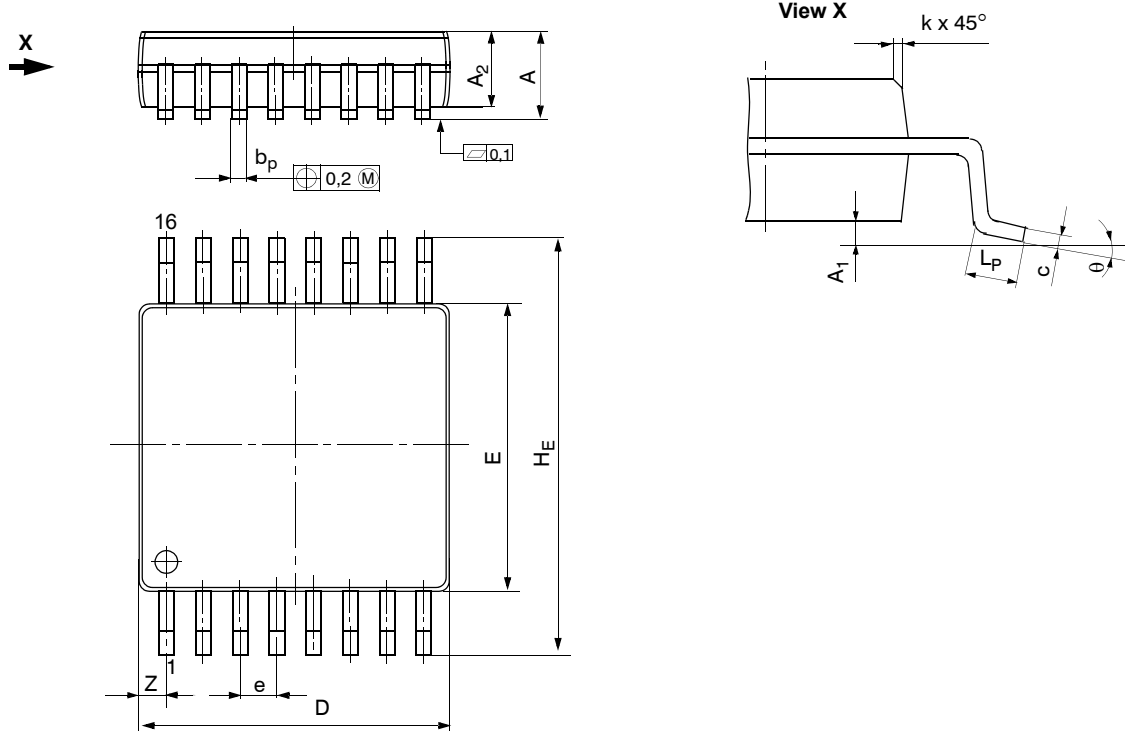
	Package SOP16 (300 mil)	MDS 773
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Dimensions in millimetres

Based on JEDEC JEP95 MS-013

1 Dimensions

Dimensions of Sub-Group B1	
A_{max}	2,65
b_{Pmin}	0,35
b_{Pmax}	0,49
e_{nom}	1,27
H_{Emin}	10,00
H_{Emax}	10,65
L_{Pmin}	0,61
Z_{max}	0,79

Dimensions of Sub-Group C1	
A_{min}	2,35
A_{1min}	0,10
A_{1max}	0,30
A_{2min}	2,25
A_{2max}	2,45
c_{min}	0,23
c_{max}	0,32
D_{min}^*	10,21
D_{max}^*	10,46
E_{min}^*	7,40
E_{max}^*	7,60
k_{min}	0,25
θ_{min}	0°
θ_{max}	8°

- 2 Weight** ≤ 0,5 g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

* without mold-flash

Zentrum Mikroelektronik Dresden		
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Check: signed Marx	Quality: signed Tina Kochan	